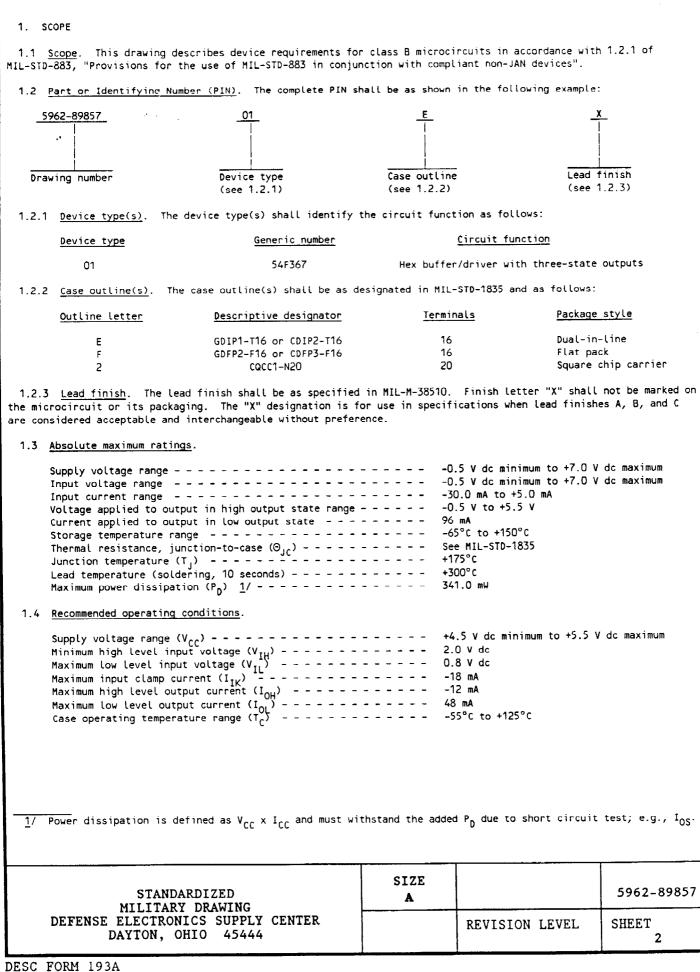
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## 2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and bulletin</u>. Unless otherwise specified, the following specification, standards, and bulletin of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARDS

MILITARY

1IL-STD-883	-	<ul> <li>Test Methods and Procedures for Microelectronics.</li> </ul>
11L-STD-1835	-	Microcircuit Case Outlines.

BULLETIN

MILITARY

MIL-BUL-103 - List of Standardized Military Drawings (SMD's).

(Copies of the specification, standards, and bulletin required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

3.1 <u>Item requirements</u>. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.

3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.

3.2.1 <u>Case outline(s)</u>. The case outline(s) shall be in accordance with 1.2.2 herein.

3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 1.

3.2.3 <u>Truth table</u>. The truth table shall be as specified on figure 2.

3.2.4 Logic diagram. The logic diagram shall be as specified on figure 3.

3.2.5 <u>Test circuit and switching waveforms</u>. The test circuit and switching waveforms shall be as specified on figure 4.

3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full case operating temperature range.

3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

3.5 <u>Marking</u>. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-BUL-103 (see 6.6 herein).

3.6 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.6 herein). The certificate of compliance submitted to DESC-EC prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.

STANDARDIZED MILITARY DRAWING	SIZE A		5962-89857
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	TABLE 1	. <u>Electrical per</u>	formance characteri	<u>stics</u> .			
Test	Symbol		ditions T <sub>C</sub> ≤ +125°C	Group A	μρΑ		Unit
	+4.5 V ≤ V		V <sub>CC</sub> ≤ +5.5 V rwise specified	Subgroups	Min	Max	
High level output voltage	V <sub>OH</sub>	V <sub>cc</sub> = 4.5 V	I <sub>OH</sub> = -1 mA	1, 2, 3	2.5		v
••		V <sub>CC</sub> = 4.5 V V <sub>IL</sub> = 0.8 V V <sub>IH</sub> = 2.0 V	I <sub>OH</sub> = -3 mA	1, 2, 3	2.4		
			I <sub>OH</sub> = -12 mA	1, 2, 3	2.0		
Low level output voitage	V <sub>OL</sub>		I <sub>OL</sub> = 48 mA	1, 2, 3		0.5	
Input clamp voltage	٧ <sub>IK</sub>	V <sub>CC</sub> = 4.5 V, I <sub>IN</sub>	<sub>1</sub> = -18 mA	1, 2, 3		-1.2	
High level input current	I IH1	$v_{cc} = 5.5 v, v_{IN}$	= 2.7 V	1, 2, 3		20	μA
	I IH2	v <sub>cc</sub> = 0.0 v, v <sub>IN</sub>	; = 7.0 V	1, 2, 3		100	
Low level input current	IIL	$v_{cc} = 5.5 v, v_{IN}$	<sub>1</sub> = 0.5 V	1, 2, 3		-20	
Off-state output current, high level voltage applied	<sup>I</sup> оzн	V <sub>CC</sub> = 5.5 V V <sub>IH</sub> = 2.0 V	V <sub>OUT</sub> = 2.7 V	1, 2, 3		50	
Off-state output current, low level voltage applied	I <sub>OZL</sub>		V <sub>OUT</sub> = 0.5 V	1, 2, 3		-50	
Short circuit output <u>1</u> / current	Ios	v <sub>cc</sub> = 5.5 v, v <sub>ol</sub>	דע 0.0 × דע	1, 2, 3	-100	-225	mA
Supply current (total)	<sup>I</sup> ссн	v <sub>cc</sub> = 5.5 v		1, 2, 3		35	
	I <sub>CCL</sub>			1, 2, 3		62	
	Iccz	1		1, 2, 3		48	
Functional tests		See 4.3.1c, V <sub>CC</sub>	= 4.5 V, 5.5 V	7,8			_
Propagation delay time,	tPLH	$c_{\perp} = 50 \text{ pF}$	V <sub>CC</sub> = 5.0 V	9	3.0	6.5	ns
I <sub>n</sub> to Y <sub>n</sub>		C <sub>L</sub> = 50 pF R <sub>L</sub> = 500Ω See figure 4	$V_{\rm CC} = 4.5 \ V, \ 5.5$	v 10, 11	3.0	8.0	
	t <sub>PHL</sub>		V <sub>CC</sub> = 5.0 V	9	3.0	7.0	
			$V_{\rm cc} = 4.5  \rm V,  5.5$	v 10, 11	3.0	8.0	
Output enable time to	t <sub>PZH</sub>		V <sub>cc</sub> = 5.0 V	9	3.0	7.5	4
high or low level			$v_{\rm CC} = 4.5 \ v, \ 5.5$	v 10, 11	3.0	9.0	
	tpzl		V <sub>CC</sub> = 5.0 V	9	3.0	8.5	
			V <sub>CC</sub> = 4.5 V, 5.5	v 10, 11	3.0	10.0	
Output disable time from	t <sub>PHZ</sub>		v <sub>cc</sub> = 5.0 v	9	2.5	6.5	
high or low level			$V_{\rm cc} = 4.5 \ V, \ 5.5$	v 10, 11	2.5	7.5	
	t <sub>PLZ</sub>		V <sub>CC</sub> = 5.0 V	9	2.5	6.0	1
			v <sub>cc</sub> = 4.5 v, 5.5	v 10, 11	2.0	7.0	
<u>1</u> / Not more than one output exceed 1 second.	should be	shorted at a time	e, and the duration	of the short-c	ircuit co	ndition s	hall no
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DESC FORM 193A JUL 91 HIO 454

Device type	0	1
Case outlines	E and F	2
Terminal number	Terminal	lsymbol
1	0E1	NC
2	I <sub>O</sub>	OE1
3	Yo	<sup>1</sup> 0
4	I <sub>1</sub>	Yo
5	۲ <sub>1</sub>	I <sub>1</sub>
6	1 <sub>2</sub>	NC
7	Y <sub>2</sub>	Y <sub>1</sub>
8	GND	<sup>1</sup> 2
9	Y <sub>3</sub>	Y <sub>2</sub>
10	I <sub>3</sub>	GND
11	Y <sub>4</sub>	NC
12	I <sub>4</sub>	Y <sub>3</sub>
13	Y <sub>5</sub>	13
14	Is	Y <sub>4</sub>
15	OE,	I <sub>4</sub>
16	UCC	NC
17		Y <sub>5</sub>
18		I <sub>5</sub>
19	<b></b> ·	
20		v <sub>cc</sub>

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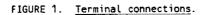
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NC = No connection

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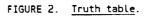


Inp	Inputs				
ŌĒ	In	Y <sub>n</sub>			
L	L	L			
L	н	н			
н	x	Z			

H = High level voltage L = Low level voltage

X = Don't care

Z = High impedance state

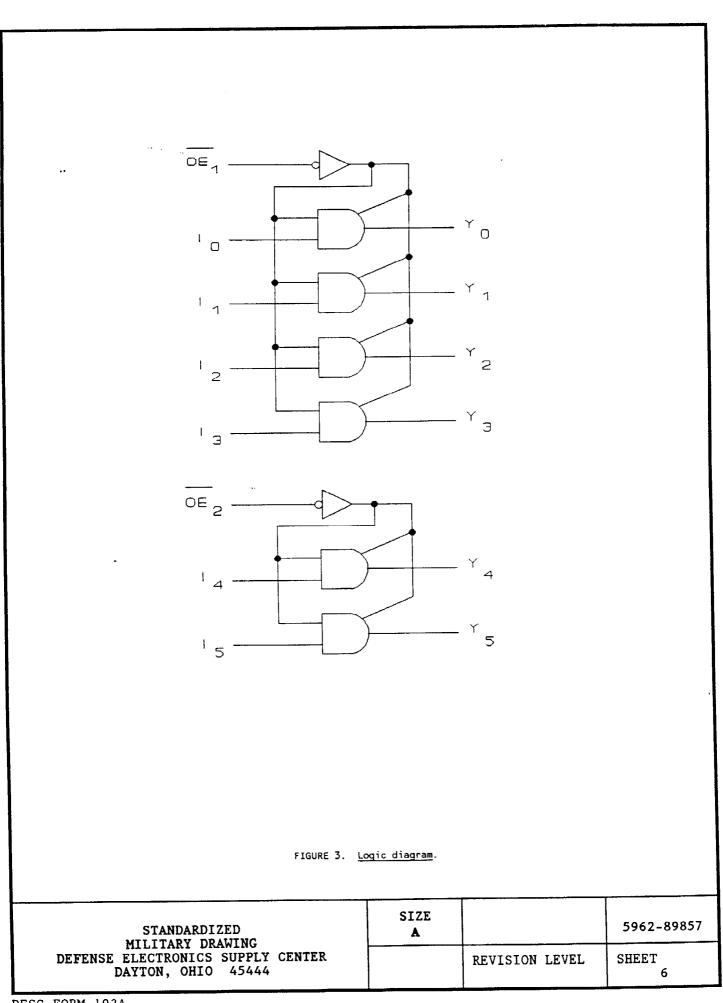


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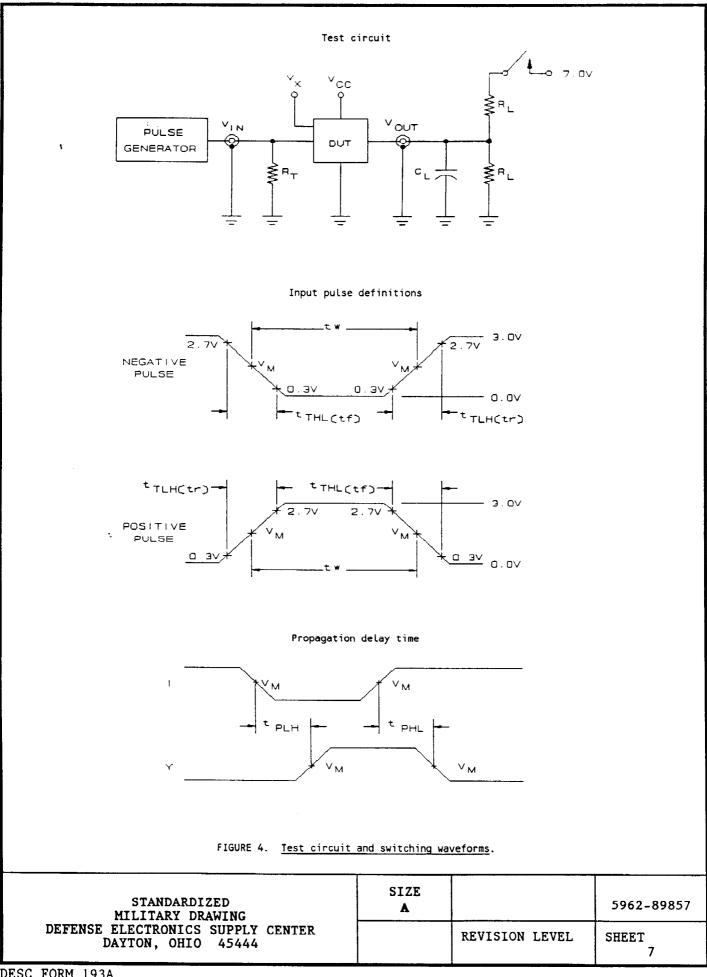
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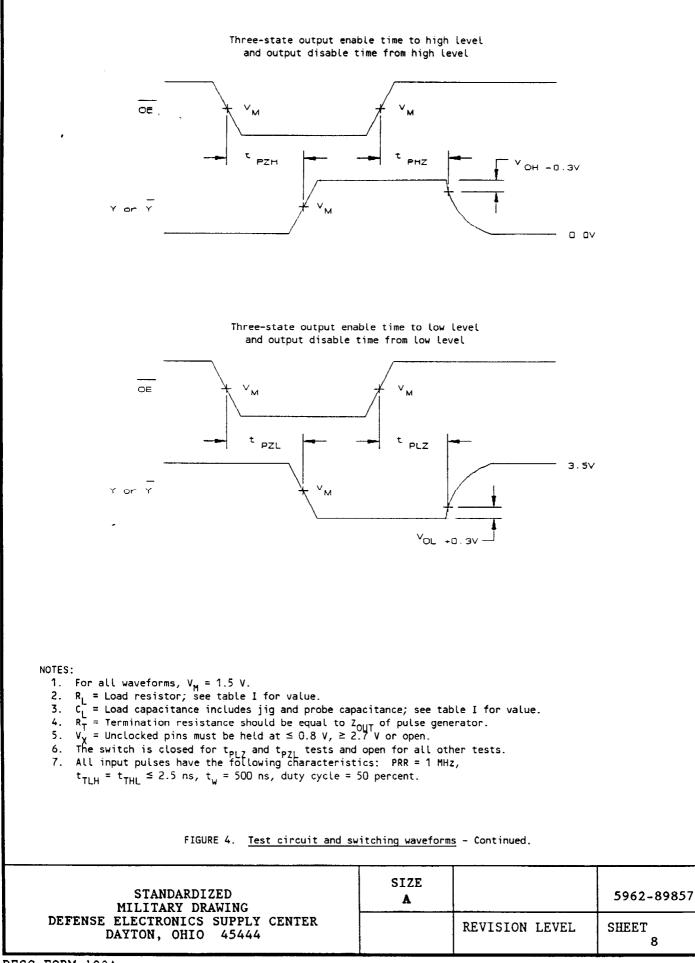
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## TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with method 5005, table I)
Interim electrical parameters (method 5004)	
Final electrical test parameters (method 5004)	1*, 2, 3, 7, 8, 9
Group A test requirements (method 5005)	1, 2, 3, 7, 8, 9, 10, 11
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

\* PDA applies to subgroup 1.

3.7 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.

3.8 <u>Notification of change</u>. Notification of change to DESC-EC shall be required in accordance with MIL-STD-883 (see 3.1 herein).

3.9 <u>Verification and review</u>. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

4. QUALITY ASSURANCE PROVISIONS

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4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).

4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:

- a. Burn-in test, method 1015 of MIL-STD-883.
  - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
  - (2)  $T_A = +125^{\circ}C$ , minimum.
- b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

4.3 <u>Quality conformance inspection</u>. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

4.3.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 4, 5, and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
- c. Subgroups 7 and 8 shall include verification of the functionality of the device.

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4.3.2 Groups C and D inspections.

a. End-point electrical parameters shall be as specified in table II herein.

b. Steady-state life test conditions, method 1005 of MIL-STD-883.

(1) Test condition A, B, C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.

(2)  $T_A = +125^{\circ}C$ , minimum.

(3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for original equipment manufacturer application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.

6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-481 using DD Form 1693, Engineering Change Proposal (Short Form).

6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DESC-EC, telephone (513) 296-6047.

6.5 <u>Comments</u>. Comments on this drawing should be directed to DESC-EC, Dayton, Ohio 45444, or telephone (513) 296-5377.

6.6 <u>Approved sources of supply</u>. Approved sources of supply are listed in MIL-BUL-103. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-EC.

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## DATE: 93-03-22

Approved sources of supply for SM0 5962-89857 are listed below for immediate acquisition only and shall be added to MIL-BUL-103 during the next revision. MIL-BUL-103 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DESC-EC. This bulletin is superseded by the next dated revision of MIL-BUL-103.

Standardized military drawing PIN	Vendor CAGE number	Vendor similar PIN <u>1</u> /
5962-8985701EX	18324	54F367/BEA
5962-8985701FX	18324	54F367/BFA
5962-89857012X	18324	54F367/B2A

<u>1</u>/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE \_\_\_\_number

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Vendor name and address

18324

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Philips Semiconductors 811 East Arques Avenue Sunnyvale, CA 94088-3409

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